Characteristics BTW68

1 Characteristics

 Table 2.
 Absolute maximum ratings (limiting values)

Symbol	Parameter			Value	Unit	
I _{T(RMS)}	On-state current rms (180° conduction angle)		T _c = 80 °C	30	Α	
IT _(AV)	Average on-state current (180° conduction angle) T		T _c = 80 °C	19	Α	
1.	Non repetitive surge peak on-state $t_p = 8.3 \text{ ms}$		T _i = 25 °C	420	Α	
ITSM	current	t _p = 10 ms	$\frac{1}{j} = 25$ C	400	Α	
l ² t	I ² t Value for fusing		T _j = 25 °C	800	A ² s	
dl/dt	Critical rate of rise of on-state current $I_G = 2 \ x \ I_{GT}$, $t_r \le 100 \ ns$	F = 60 Hz	T _j = 125 °C	100	A/μs	
I _{GM}	Peak gate current	t _p = 20 μs	T _j = 125 °C	8	Α	
P _{G(AV)}	Average gate power dissipation $T_j = 125 ^{\circ}\text{C}$			1	W	
T _{stg} T _j	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 125	°C	
V _{RGM}	Maximum peak reverse gate voltage			5	V	

Table 3. Electrical characteristics ($T_j = 25$ °C, unless otherwise specified)

Symbol	Test conditions	Value	Unit		
I _{GT}	$V_D = 12 \text{ V}, R_1 = 33 \Omega$		MIN.	50	mA
V _{GT}	v _D = 12 v, n _L = 33 32		MAX.	1.5	V
V _{GD}	$V_D = V_{DRM}$, $R_L = 3.3 \text{ k}\Omega$ $T_j = 125 \text{ °C}$			0.2	V
t _{gt}	$V_D = V_{DRM}$, $I_G = 200$ mA, $dI_G/dt = 1.5$ A/ μ s			2	μs
I _H	I _T = 500 mA, gate open			75	mA
ΙL	I _G = 1.2 x I _{GT}			40	mA
dV/dt	$V_{D} = 67 \% V_{DRM}$ $V_{DRM} = 800 V$	T = 125 °C	MIN.	500	V/µs
u v/ut	gate open $V_{DRM} = 1000 \text{ V}$	7 1 _j = 125 0	IVIIIN.	250	ν/μ5
V_{TM}	$I_{TM} = 60 \text{ A}, t_p = 380 \mu \text{s}$		MAX.	2.1	V
I _{DRM}	V	T _j = 25 °C	MAX.	20	μΑ
I _{RRM}	$V_{DRM} = V_{RRM}$	T _j = 125 °C	IVIAA.	6	mA
t _q	$V_D = 67\% \ V_{DRM}, \ I_{TM} = 60 \ A, \ V_R = 75 \ V$ $dI_{TM}/dt = 30 \ A/\mu s, \ dV_D/dt = 20 \ V/\mu s$	T _j = 125 °C	TYP.	100	μs

Table 4. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case (D.C.)	1.1	°C/W
R _{th(j-a)}	Junction to ambient	50	°C/W

BTW68 Characteristics

Figure 1. Maximum average power dissipation versus average on-state current

Figure 2. Correlation between maximum average power dissipation and maximum allowable temperature

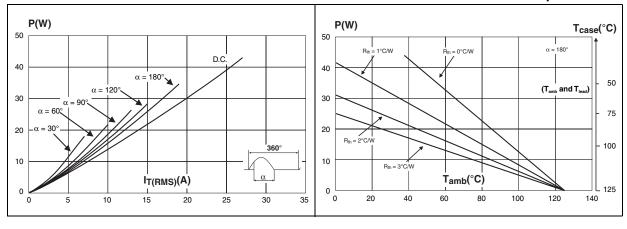


Figure 3. Average on-state current versus case Figure 4. temperature

Relative variation of thermal impedance versus pulse duration

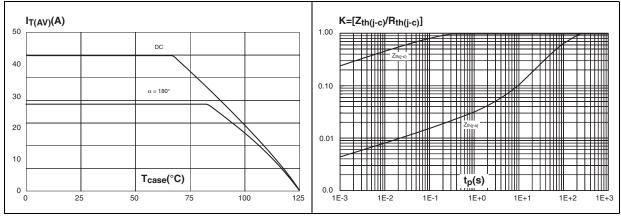
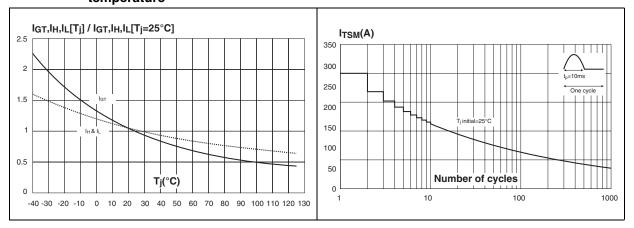


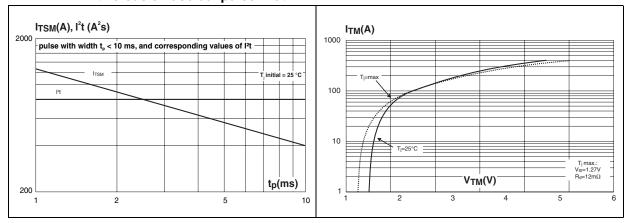
Figure 5. Relative variation of gate trigger current versus junction temperature

Figure 6. Surge peak on-state current versus number of cycles



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Figure 7. Non repetitive surge peak on-state Figure 8. Current and corresponding value of I^2t versus sinusoidal pulse width On-state characteristics (maximum values)



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2 Ordering information scheme

Figure 9. Ordering information scheme

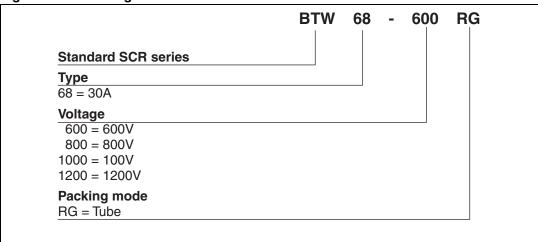


Table 5. Product Selector

Part numbers	Voltage (xxx)				Sensitivity	Package
	600 V	800 V	1000 V	1200 V		
BTW68-600RG	Х					
BTW68-800RG		Х			50 mA	TOP3 Ins.
BTW68-1000RG			Х		30 IIIA	TOF5 IIIS.
BTW68-1200RG				Х		

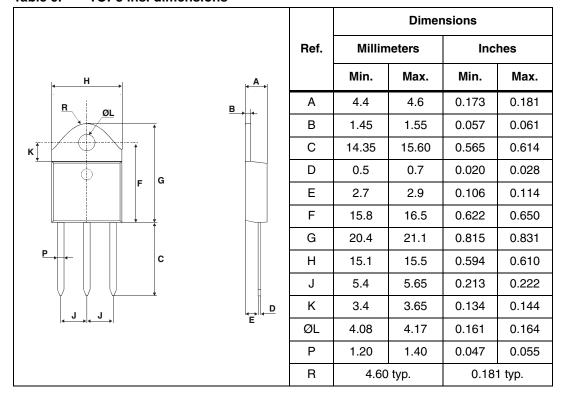
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3 Package information

- Epoxy meets UL94,V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 6. TOP3 ins. dimensions



4 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
BTW68-600RG	BTW68-600				
BTW68-800RG	BTW68-800	TOP3 ins.	4.5 g	30	Tube
BTW68-1000RG	BTW68-1000	101 5 1115.	4.5 g	30	Tube
BTW68-1200RG	BTW68-1200				

5 Revision history

Table 8. Document revision history

Date	Revision Changes	
Mar-1995	1	Initial release.
13-Feb-2006	2	TOP3 Insulated delivery mode changed from bulk to tube. ECOPACK statement added.
29-Jul-2010	3	Deleted part number BTW68-200RG. Updated <i>Table 2</i> , <i>Figure 7</i> and alpha angle in <i>Figure 1</i> .

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